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02166766957 - 02166766927



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تهران پاساژ امجد طبقه 1 واحد 16



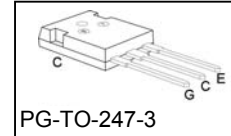
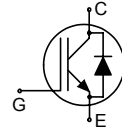
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Reverse Conducting IGBT with monolithic body diode

Features:

- Powerful monolithic Body Diode with very low forward voltage
- Body diode clamps negative voltages
- Trench and Fieldstop technology for 1200 V applications offers :
 - very tight parameter distribution
 - high ruggedness, temperature stable behavior
- NPT technology offers easy parallel switching capability due to positive temperature coefficient in $V_{CE(sat)}$
- Low EMI
- Qualified according to JEDEC¹ for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models : <http://www.infineon.com/igbt/>



Applications:

- Inductive Cooking
- Soft Switching Applications

Type	V_{CE}	I_C	$V_{CE(sat)}, T_j=25^\circ\text{C}$	$T_{j,max}$	Marking	Package
IHW25N120R2	1200V	25A	1.6V	175°C	H25R1202	PG-TO-247-3

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CE}	1200	V
DC collector current $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_C	50 25	A
Pulsed collector current, t_p limited by $T_{j,max}$	I_{Cpuls}	75	
Turn off safe operating area ($V_{CE} \leq 1200\text{V}$, $T_j \leq 175^\circ\text{C}$)	-	75	
Diode forward current $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_F	50 25	
Diode pulsed current, t_p limited by $T_{j,max}$	I_{Fpuls}	75	
Diode surge non repetitive current, t_p limited by $T_{j,max}$ $T_C = 25^\circ\text{C}$, $t_p = 10\text{ms}$, sine halfwave $T_C = 25^\circ\text{C}$, $t_p \leq 2.5\mu\text{s}$, sine halfwave $T_C = 100^\circ\text{C}$, $t_p \leq 2.5\mu\text{s}$, sine halfwave	I_{FSM}	50 130 120	
Gate-emitter voltage	V_{GE}	± 20	V
Transient Gate-emitter voltage ($t_p < 10 \mu\text{s}$, $D < 0.01$)		± 25	
Power dissipation $T_C = 25^\circ\text{C}$	P_{tot}	365	W
Operating junction temperature	T_j	-40...+175	°C
Storage temperature	T_{stg}	-55...+175	
Soldering temperature, 1.6mm (0.063 in.) from case for 10s	-	260	

¹ J-STD-020 and JEDEC-022

Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
Characteristic				
IGBT thermal resistance, junction – case	R_{thJC}		0.41	K/W
Diode thermal resistance, junction – case	R_{thJCD}		0.41	
Thermal resistance, junction – ambient	R_{thJA}		40	

Electrical Characteristic, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=500\mu A$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C=25A$				
		$T_j=25^{\circ}C$	-	1.6	1.8	
		$T_j=150^{\circ}C$	-	1.95	-	
		$T_j=175^{\circ}C$	-	2.0	-	
Diode forward voltage	V_F	$V_{GE}=0V, I_F=25A$				
		$T_j=25^{\circ}C$	-	1.5	1.75	
		$T_j=150^{\circ}C$	-	1.75	-	
		$T_j=175^{\circ}C$	-	1.8	-	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=0.58mA, V_{CE}=V_{GE}$	5.1	5.8	6.4	
Zero gate voltage collector current	I_{CES}	$V_{CE}=1200V, V_{GE}=0V$				μA
		$T_j=25^{\circ}C$	-	-	4	
		$T_j=175^{\circ}C$	-	-	2500	
Gate-emitter leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=20V$	-	-	100	nA
Transconductance	g_{fs}	$V_{CE}=20V, I_C=25A$	-	16.3	-	S
Integrated gate resistor	R_{Gint}			none		Ω

Dynamic Characteristic

Input capacitance	C_{iss}	$V_{CE}=25V,$	-	2342	-	pF
Output capacitance	C_{oss}	$V_{GE}=0V,$	-	68.7	-	
Reverse transfer capacitance	C_{rss}	$f=1MHz$	-	55.5	-	
Gate charge	Q_{Gate}	$V_{CC}=960V, I_C=25A$ $V_{GE}=15V$	-	60.7	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E		-	13	-	nH

Switching Characteristic, Inductive Load, at $T_j=25^\circ C$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic						
Turn-off delay time	$t_{d(off)}$	$T_j=25^{\circ}C,$ $V_{CC}=600V, I_C=25A$ $V_{GE}=0/15V,$ $R_G=10\Omega,$	-	324	-	ns
Fall time	t_f		-	55.8	-	
Turn-on energy	E_{on}		-	-	-	
Turn-off energy	E_{off}		-	1.59	-	
Total switching energy	E_{ts}		-	1.59	-	mJ

Switching Characteristic, Inductive Load, at $T_j=175^\circ C$

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
IGBT Characteristic						
Turn-off delay time	$t_{d(off)}$	$T_j=175^{\circ}C$ $V_{CC}=600V, I_C=25A,$ $V_{GE}= 0 / 15V,$ $R_G= 10\Omega,$	-	373	-	ns
Fall time	t_f		-	90.6	-	
Turn-on energy	E_{on}		-	-	-	
Turn-off energy	E_{off}		-	2.54	-	
Total switching energy	E_{ts}			-	2.54	-

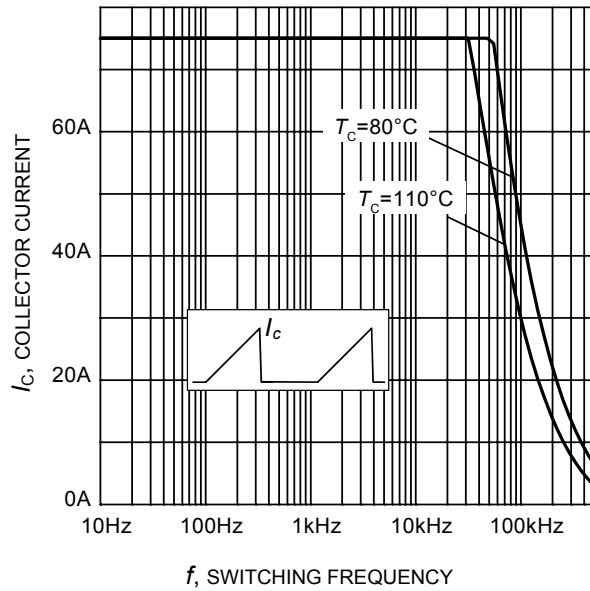


Figure 1. Collector current as a function of switching frequency for hard switching (turn-off)
 $(T_j \leq 175^\circ\text{C}, D = 0.5, V_{CE} = 600\text{V}, V_{GE} = 0/+15\text{V}, R_G = 10\Omega)$

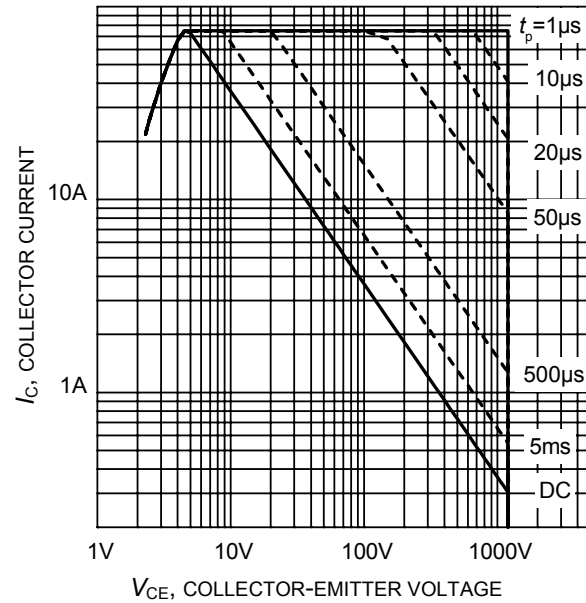


Figure 2. IGBT Safe operating area
 $(D = 0, T_C = 25^\circ\text{C}, T_j \leq 175^\circ\text{C}; V_{GE} = 15\text{V})$

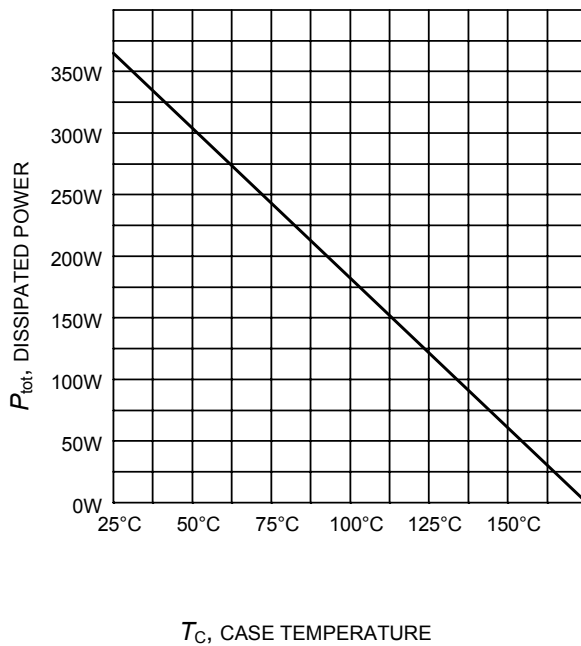


Figure 3. Power dissipation as a function of case temperature
 $(T_j \leq 175^\circ\text{C})$

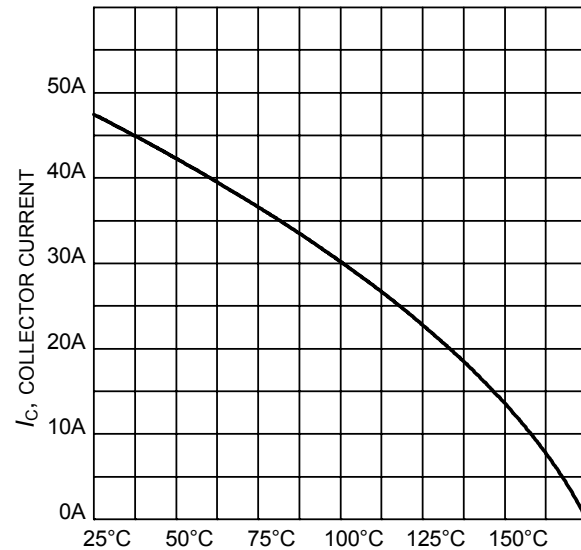


Figure 4. DC Collector current as a function of case temperature
 $(V_{GE} \geq 15\text{V}, T_j \leq 175^\circ\text{C})$

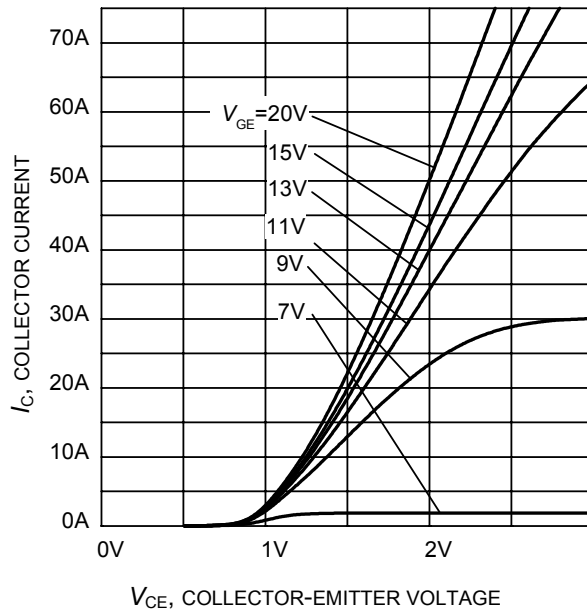


Figure 5. Typical output characteristic
($T_j = 25^\circ\text{C}$)

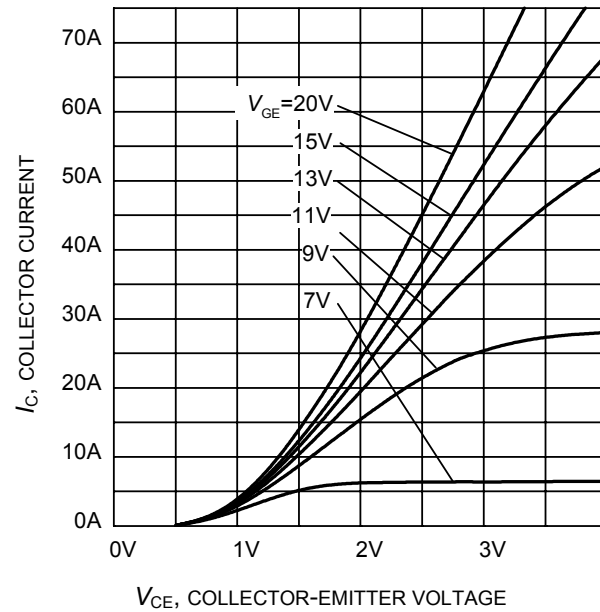


Figure 6. Typical output characteristic
($T_j = 175^\circ\text{C}$)

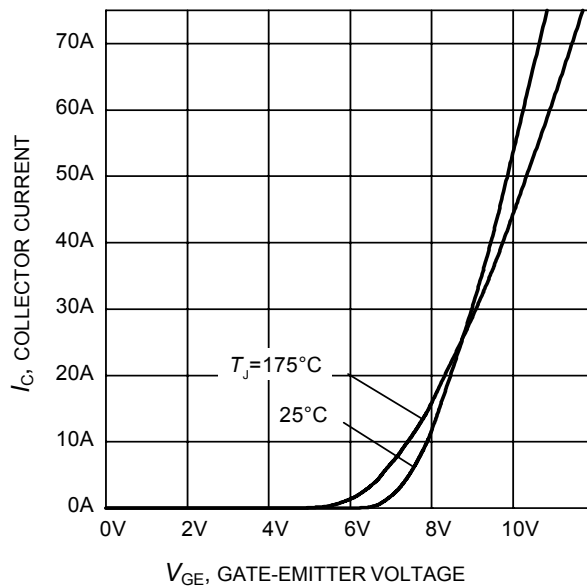


Figure 7. Typical transfer characteristic
($V_{CE} = 20\text{V}$)

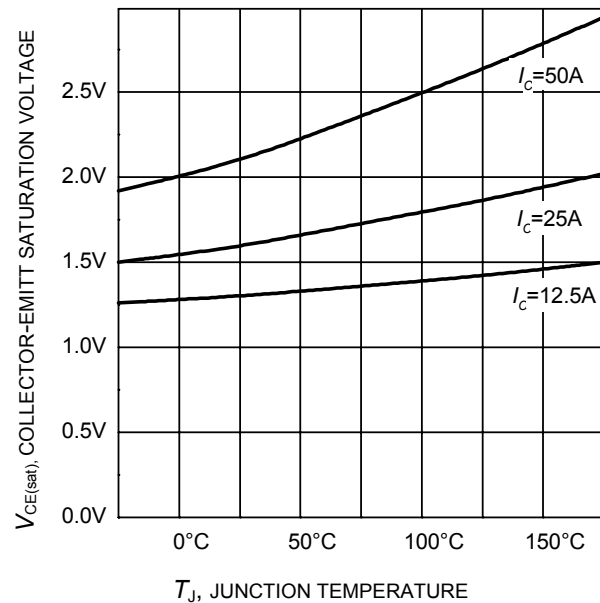


Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature
($V_{GE} = 15\text{V}$)

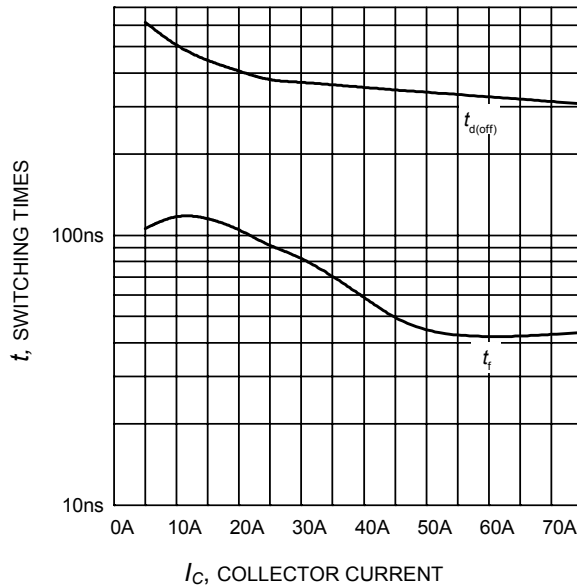


Figure 9. Typical switching times as a function of collector current
(inductive load, $T_J=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_G=10\Omega$, Dynamic test circuit in Figure E)

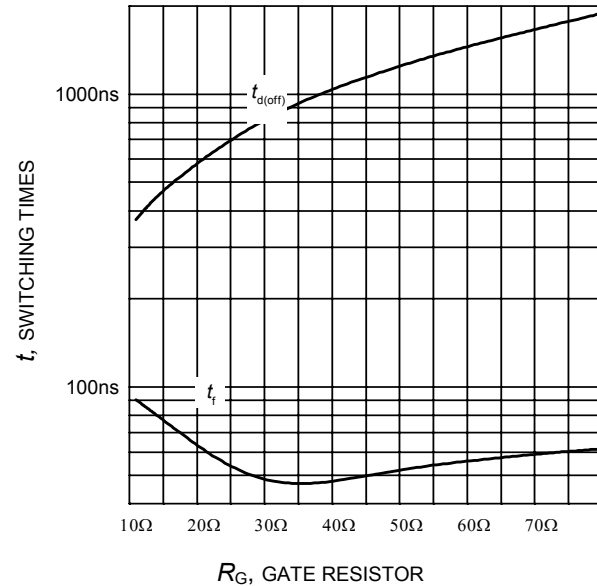


Figure 10. Typical switching times as a function of gate resistor
(inductive load, $T_J=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=25\text{A}$, Dynamic test circuit in Figure E)

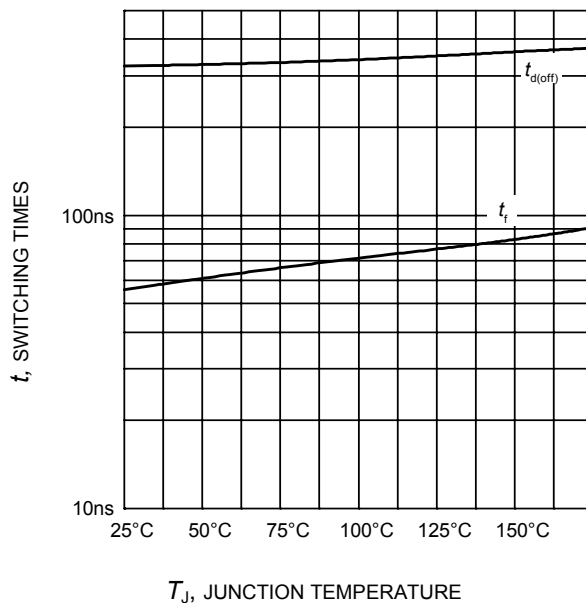


Figure 11. Typical switching times as a function of junction temperature
(inductive load, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=25\text{A}$, $R_G=10\Omega$, Dynamic test circuit in Figure E)

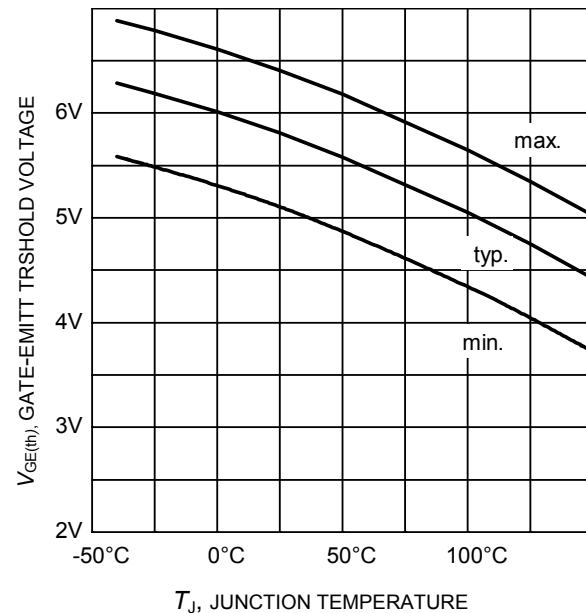


Figure 12. Gate-emitter threshold voltage as a function of junction temperature
($I_C = 0.6\text{mA}$)

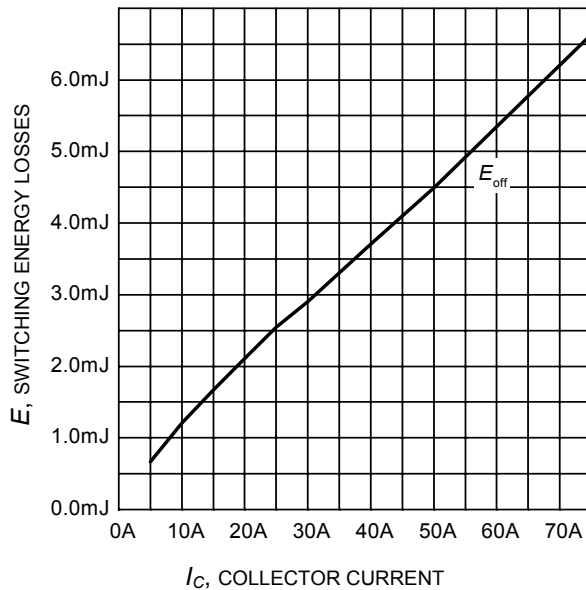


Figure 13. Typical turn-off energy as a function of collector current
(inductive load, $T_J=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_G=10\Omega$, Dynamic test circuit in Figure E)

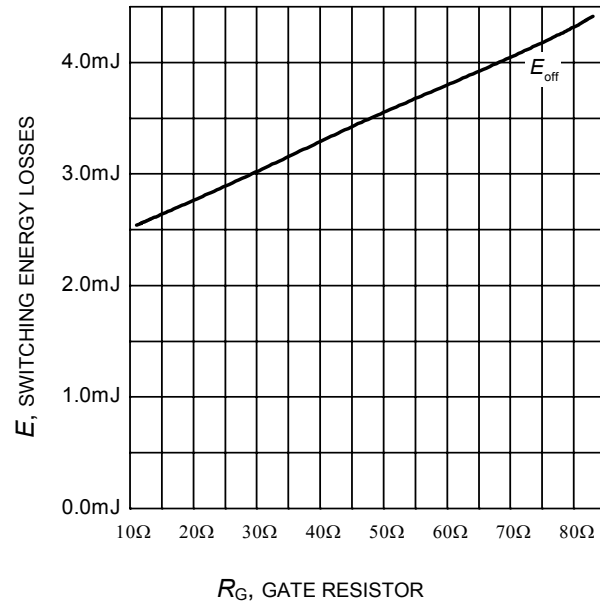


Figure 14. Typical turn-off energy as a function of gate resistor
(inductive load, $T_J=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=25\text{A}$, Dynamic test circuit in Figure E)

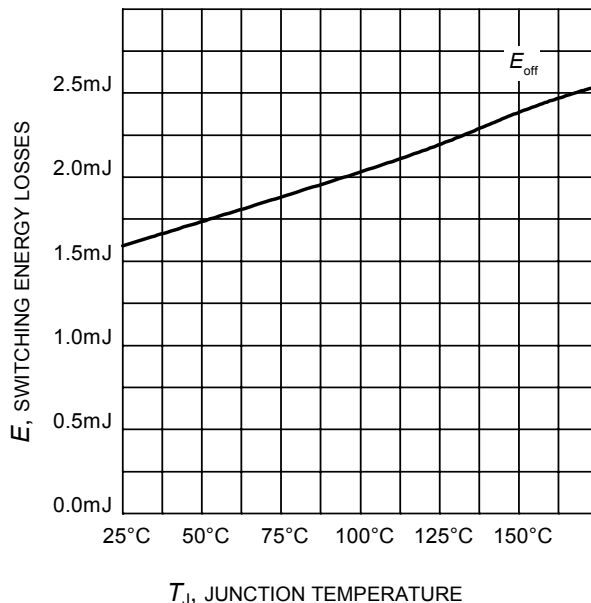


Figure 15. Typical turn-off energy as a function of junction temperature
(inductive load, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=25\text{A}$, $R_G=10\Omega$, Dynamic test circuit in Figure E)

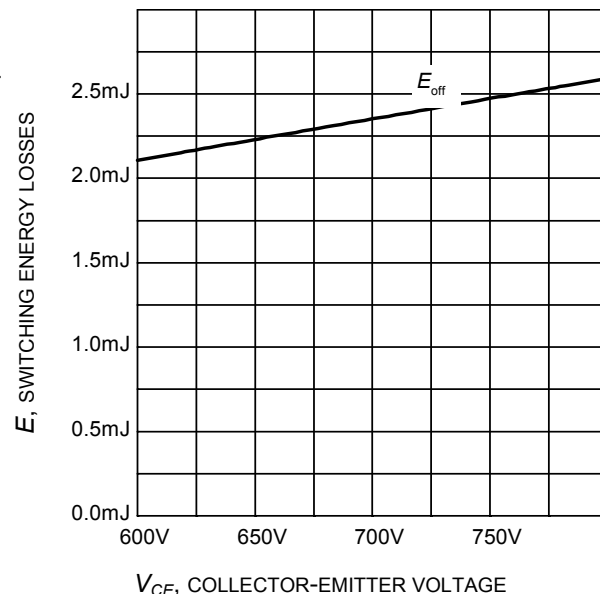


Figure 16. Typical turn-off energy as a function of collector emitter voltage
(inductive load, $T_J=175^\circ\text{C}$, $V_{GE}=0/15\text{V}$, $I_C=20\text{A}$, $R_G=10\Omega$, Dynamic test circuit in Figure E)

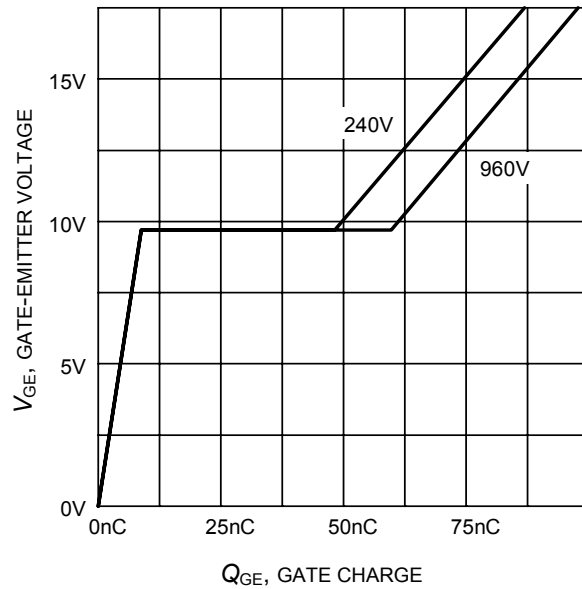


Figure 17. Typical gate charge
($I_C = 25\text{ A}$)

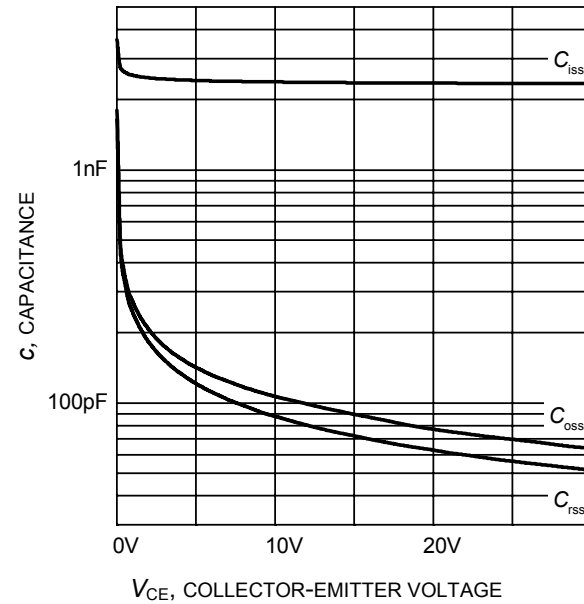


Figure 18. Typical capacitance as a function of collector-emitter voltage
($V_{GE} = 0\text{ V}$, $f = 1\text{ MHz}$)

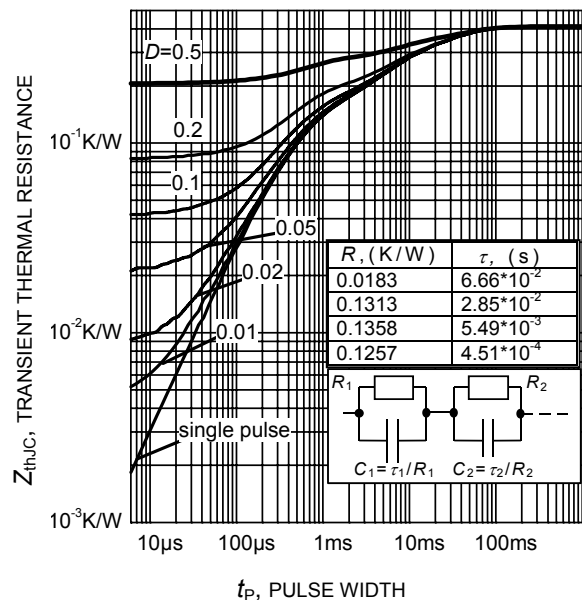


Figure 19. IGBT transient thermal resistance
($D = t_p / T$)

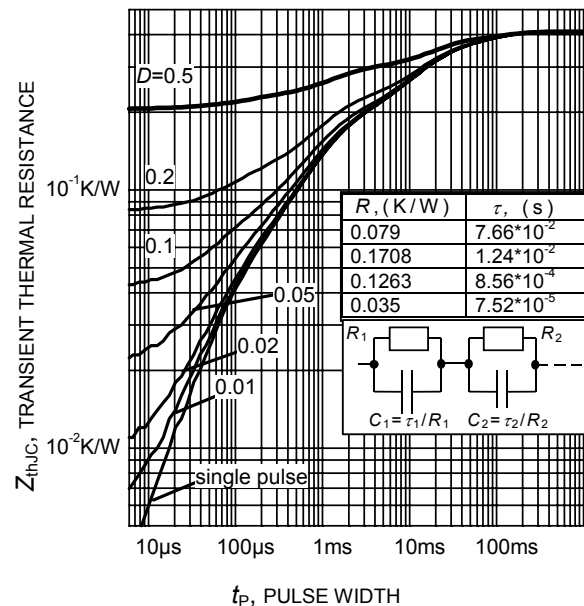


Figure 20. Diode transient thermal impedance as a function of pulse width
($D = t_p / T$)

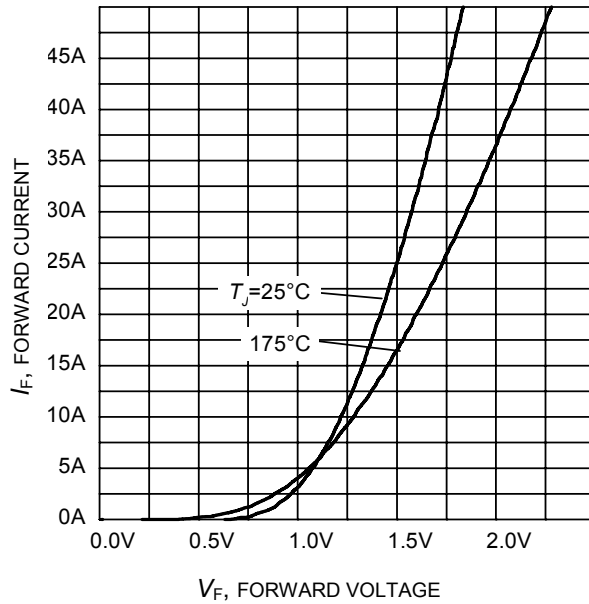


Figure 21. Typical diode forward current as a function of forward voltage

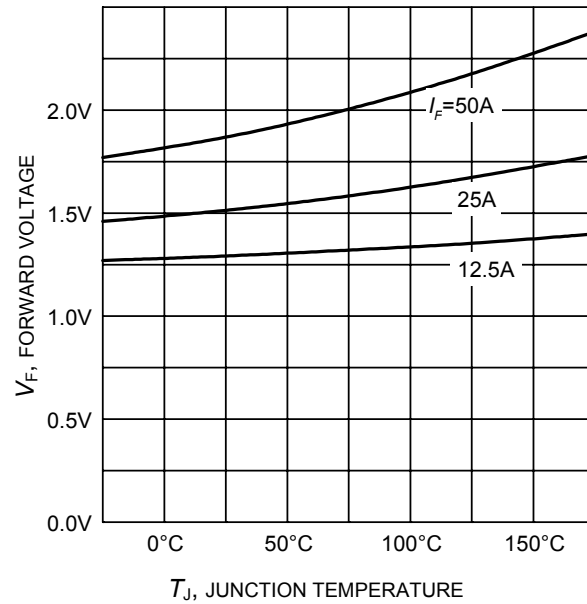
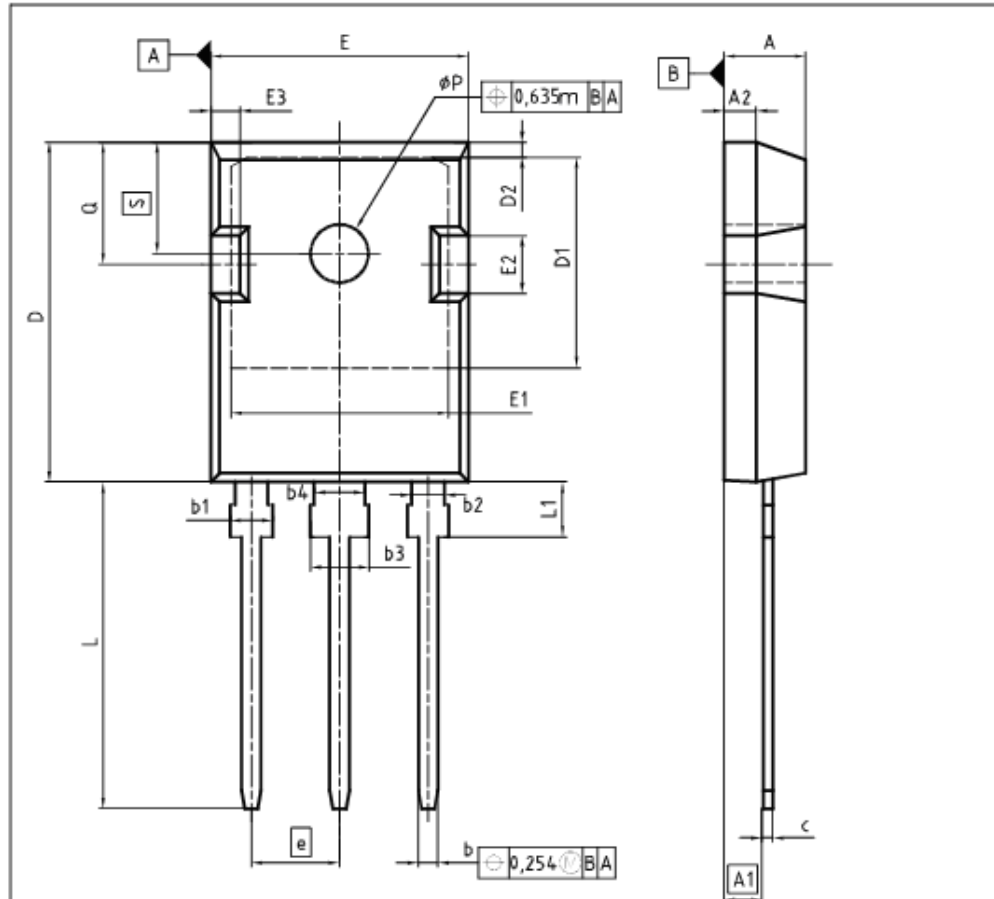


Figure 22. Typical diode forward voltage as a function of junction temperature

TO247-3



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.83	5.21	0.190	0.205
A1	2.27	2.54	0.089	0.100
A2	1.85	2.16	0.073	0.085
b	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
c	0.55	0.68	0.022	0.027
D	20.80	21.10	0.819	0.831
D1	16.25	17.65	0.640	0.695
D2	0.95	1.35	0.037	0.053
E	15.70	16.13	0.618	0.635
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.00	2.60	0.039	0.102
e	5.44		0.214	
N	3		3	
L	19.80	20.32	0.780	0.800
L1	4.10	4.47	0.161	0.176
ϕP	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248

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SCALE
0 5 7.5mm

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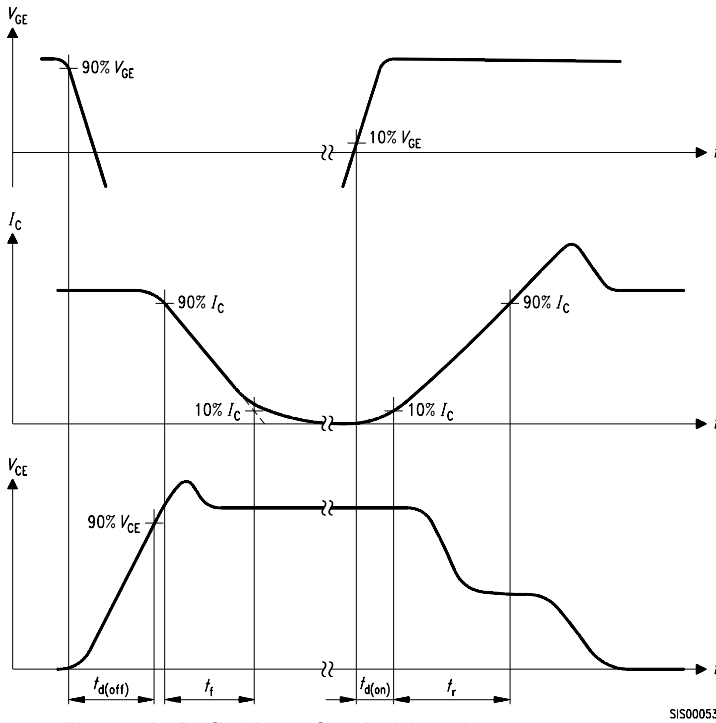


Figure A. Definition of switching times

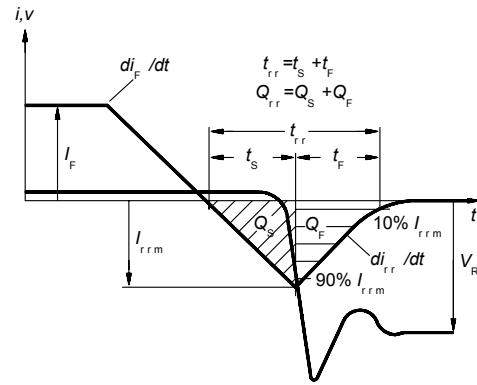


Figure C. Definition of diodes switching characteristics

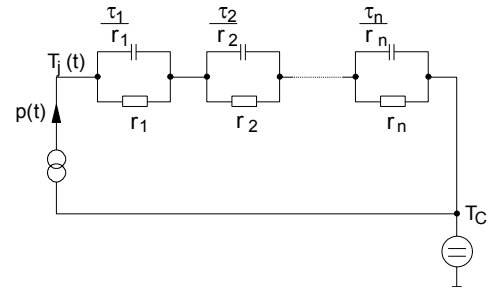


Figure D. Thermal equivalent circuit

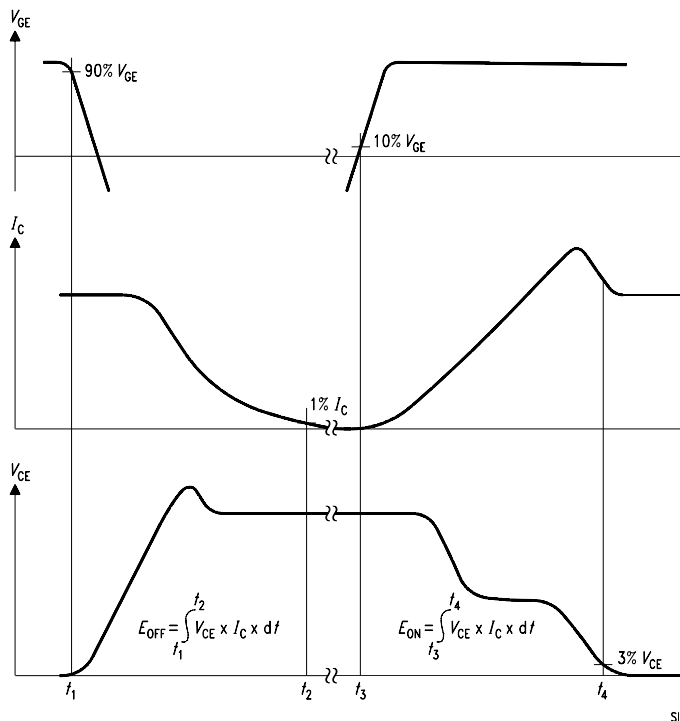


Figure B. Definition of switching losses

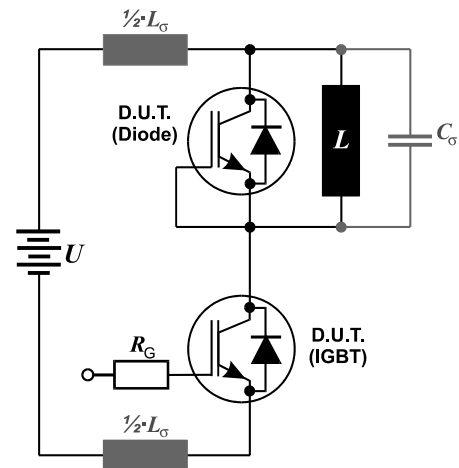


Figure E. Dynamic test circuit

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